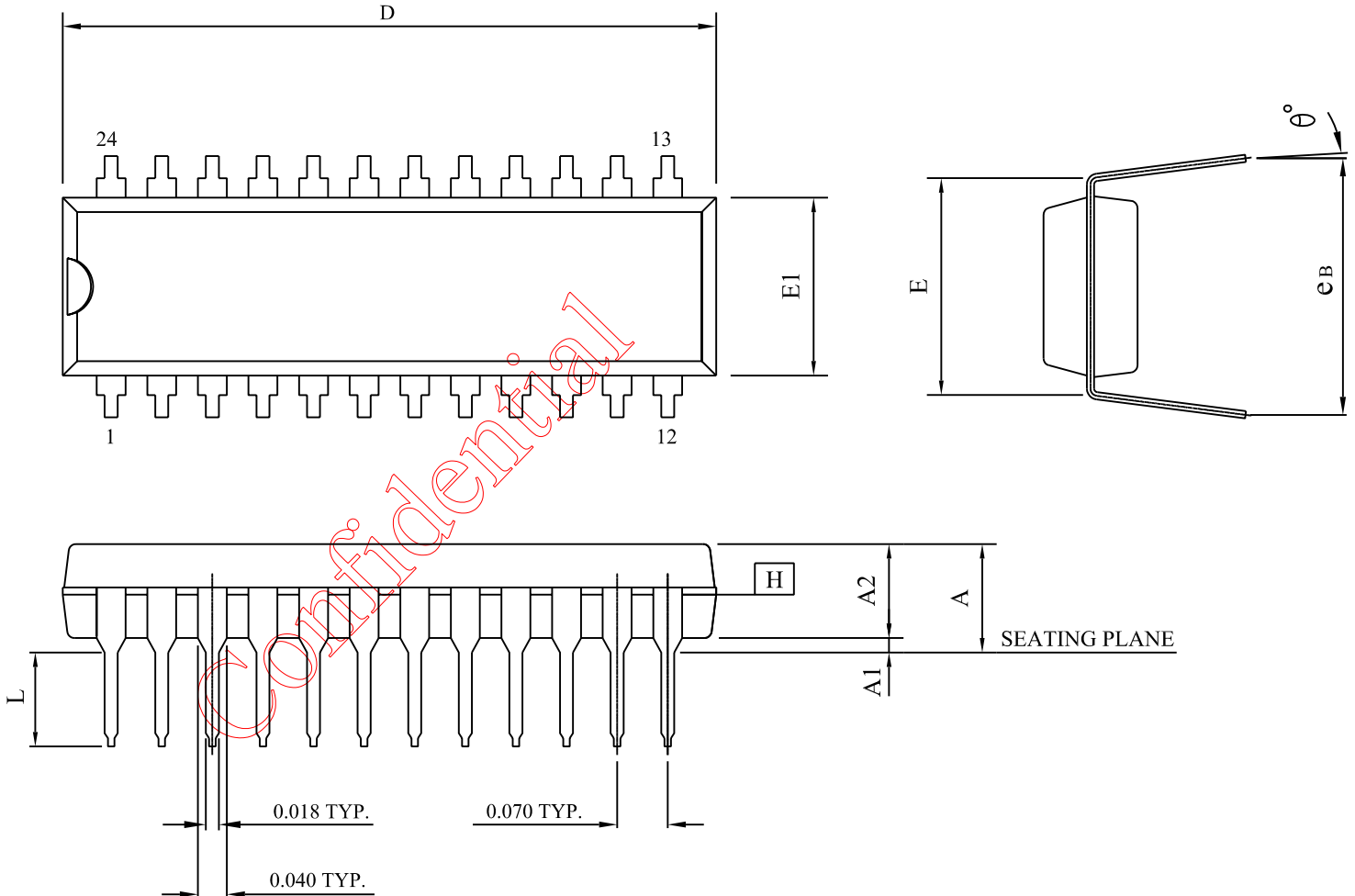


Title: Package outline for 24Shrink PDIP-300mil (Pitch 0.07 inch)



NOTES:

1. JEDEC OUTLINE : MS-019 AF
2. "D", "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH.
3. eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
4. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
5. DISTANCE BETWEEN LEADS INCLUDING DAM BAR PROTRUSIONS TO BE .005 INCH MINIMUM.
6. DATUM PLANE  $\square$  COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY.
7. PLATING THICKNESS : 0.3 ~ 0.8 MIL.

SYMBOL UNIT		A	A1	A2	D	E	E1	L	e <sub>B</sub>	θ°
inch	Min.	-	0.015	0.125	0.880	0.300 BSC.	0.245	0.115	0.335	0°
	Nom.	-	-	0.130	0.900		0.250	0.130	0.355	7°
	Max.	0.210	-	0.135	0.920		0.255	0.150	0.375	10°

DWG. NO.	ORIGINATOR	ISSUE DATE	REV.
PC600-0019	Yuki Yeh	24-Apr.-'08	0